

P-Channel 100 V (D-S) MOSFET

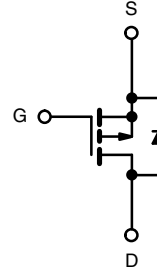
| PRODUCT SUMMARY | | | |
|---------------------|------------------------------------|--------------------|-----------------------|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) | Q _g (Typ.) |
| - 100 | 0.040 at V _{GS} = - 10 V | - 37 | 54 nC |
| | 0.050 at V _{GS} = - 4.5 V | - 32 | |

FEATURES

- TrenchFET[®] Power MOSFET



RoHS
COMPLIANT
HALOGEN
FREE



P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted) | | | | |
|---|------------------------|-----------------------------------|------------------------|------|
| Parameter | | Symbol | Limit | Unit |
| Drain-Source Voltage | | V _{DS} | - 100 | V |
| Gate-Source Voltage | | V _{GS} | ± 20 | |
| Continuous Drain Current (T _J = 150 °C) ^b | T _C = 25 °C | I _D | - 37 | A |
| | T _C = 70 °C | | - 29.5 | |
| | T _A = 25 °C | | - 10 ^{b, c} | |
| | T _A = 70 °C | | - 8.2 ^{b, c} | |
| Pulsed Drain Current | | I _{DM} | - 150 | |
| Continuous Source Current (Diode Conduction) | T _C = 25 °C | I _S | - 50 ^a | |
| | T _A = 25 °C | | - 6.75 ^{b, c} | |
| Avalanche Current | L = 0.1 mH | I _{AS} | - 35 | |
| Single Pulse Avalanche Energy | | E _{AS} | 61 | mJ |
| Maximum Power Dissipation | T _C = 25 °C | P _D | 113.6 | W |
| | T _C = 70 °C | | 72.7 | |
| | T _A = 25 °C | | 6.9 ^{b, c} | |
| | T _A = 70 °C | | 4.4 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------|---------------------------------|-------------------|-------|------|
| Parameter | | Symbol | Limit | Unit |
| Junction-to-Ambient | PCB Mount (TO-263) ^c | R _{thJA} | 40 | °C/W |
| Junction-to-Case (Drain) | | R _{thJC} | 2.1 | |

Notes:

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 10 s.

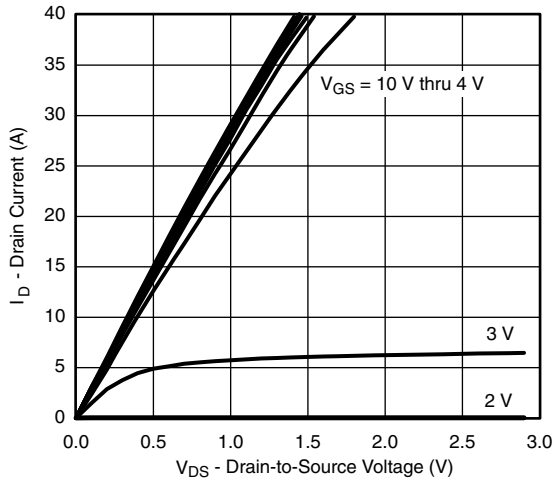
| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | |
|--|-------------------------|---|------|-------|-----------|---------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$ | -100 | | | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D = -250\text{ }\mu\text{A}$ | | -109 | | mV/°C |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 5.9 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$ | -1 | | -3 | V |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$ | | | -1 | μA |
| | | $V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$ | | | -10 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = -10\text{ V}$ | -40 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}, I_D = -9.2\text{ A}$ | | 0.040 | | Ω |
| | | $V_{GS} = -4.5\text{ V}, I_D = -7.7\text{ A}$ | | 0.050 | | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = -15\text{ V}, I_D = -9.2\text{ A}$ | | 38 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = -50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | | 3800 | | pF |
| Output Capacitance | C_{oss} | | | 185 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 135 | | |
| Total Gate Charge | Q_g | $V_{DS} = -50\text{ V}, V_{GS} = -10\text{ V}, I_D = -9.2\text{ A}$ | | 106 | 160 | nC |
| | | | | 54 | 81 | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -50\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -9.2\text{ A}$ | | 14 | | |
| Gate-Drain Charge | Q_{gd} | | | 26 | | |
| Gate Resistance | R_g | $f = 1\text{ MHz}$ | | 4 | | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -50\text{ V}, R_L = 6.5\text{ }\Omega$ $I_D \cong -7.7\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$ | | 15 | 25 | ns |
| Rise Time | t_r | | | 20 | 30 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 110 | 165 | |
| Fall Time | t_f | | | 100 | 150 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -50\text{ V}, R_L = 6.5\text{ }\Omega$ $I_D \cong -7.7\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$ | | 42 | 65 | ns |
| | | | | | 160 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 100 | 150 | |
| Fall Time | t_f | | | 100 | 150 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | $T_C = 25\text{ }^\circ\text{C}$ | | | -50 | A |
| Pulse Diode Forward Current ^a | I_{SM} | | | | -40 | |
| Body Diode Voltage | V_{SD} | $I_S = -7.7\text{ A}$ | | -0.8 | -1.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = -7.7\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$ | | 60 | 90 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 150 | 225 | nC |
| Reverse Recovery Fall Time | t_a | | | 46 | | ns |
| Reverse Recovery Rise Time | t_b | | | 14 | | |

Notes:

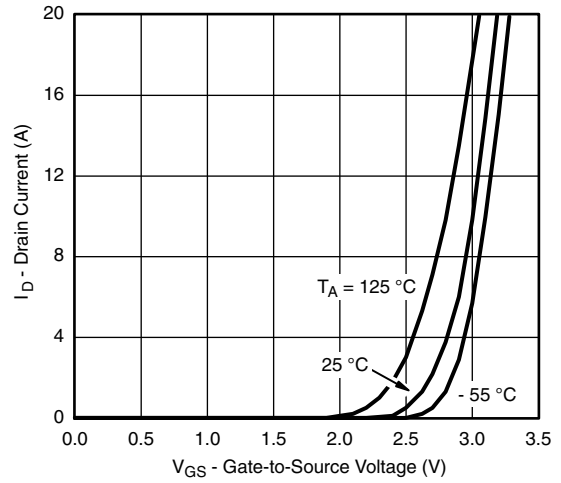
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

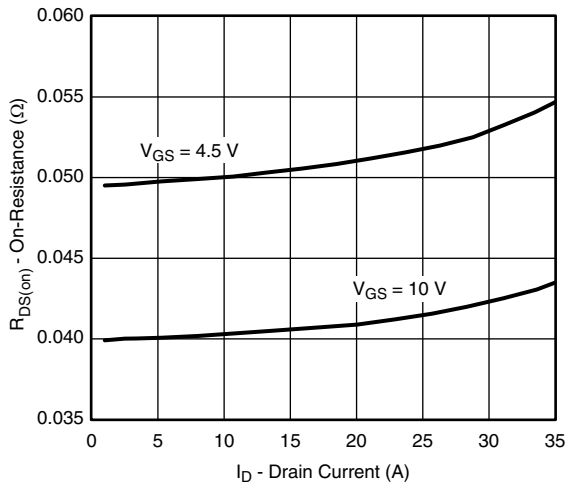
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



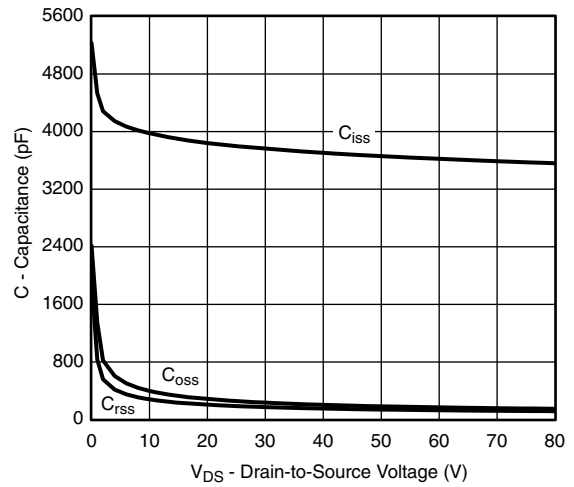
Output Characteristics



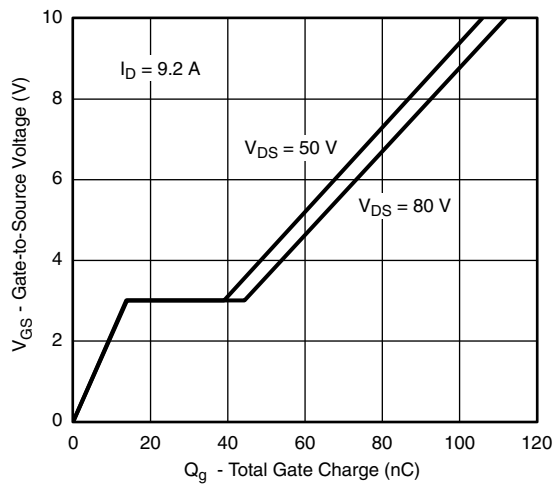
Transfer Characteristics



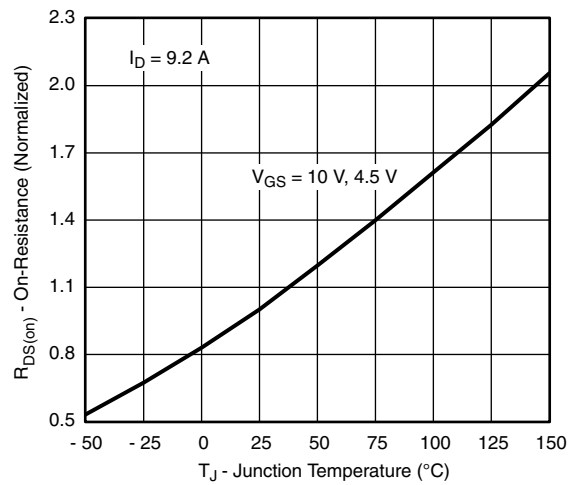
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

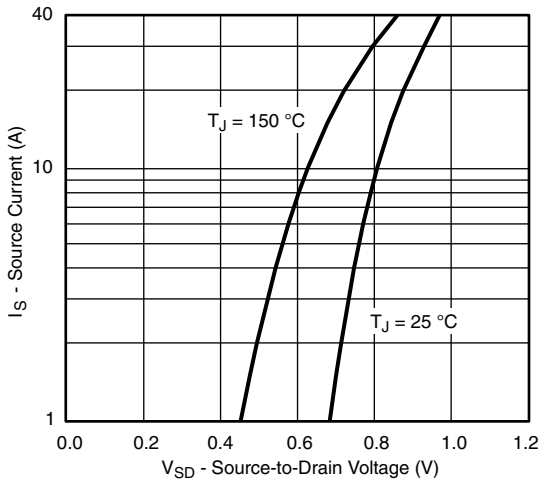


Gate Charge

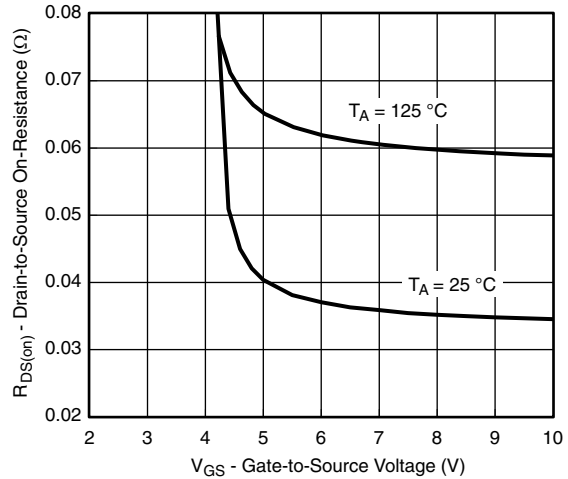


On-Resistance vs. Junction Temperature

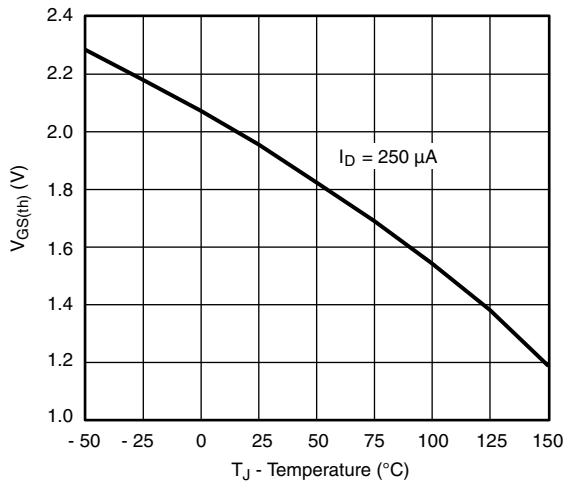
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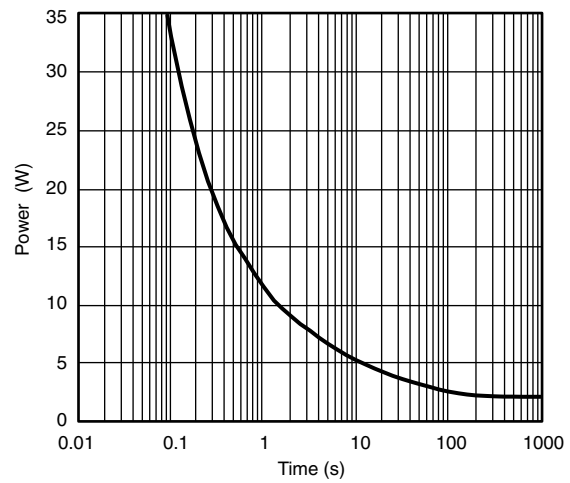
Source-Drain Diode Forward Voltage



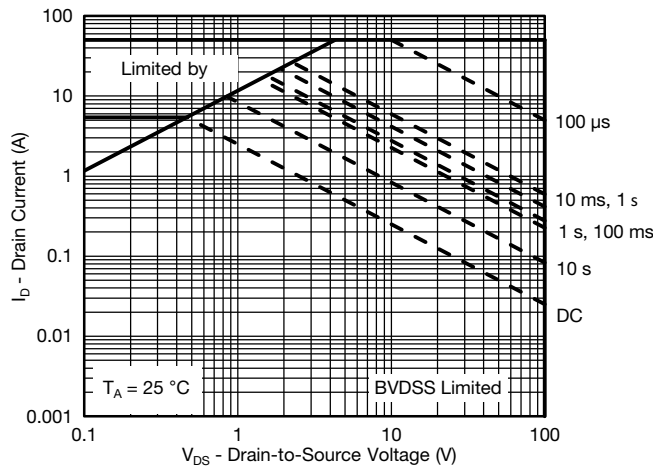
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

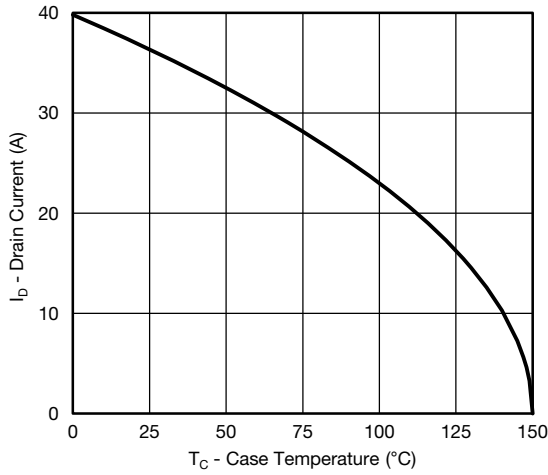


Single Pulse Power, Junction-to-Ambient

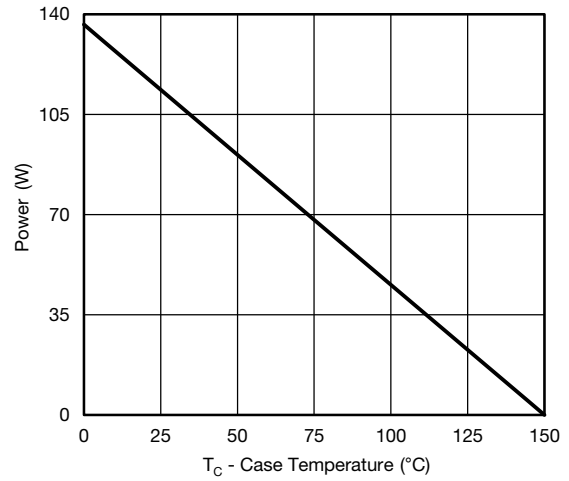


Safe Operating Area, Junction-to-Ambient

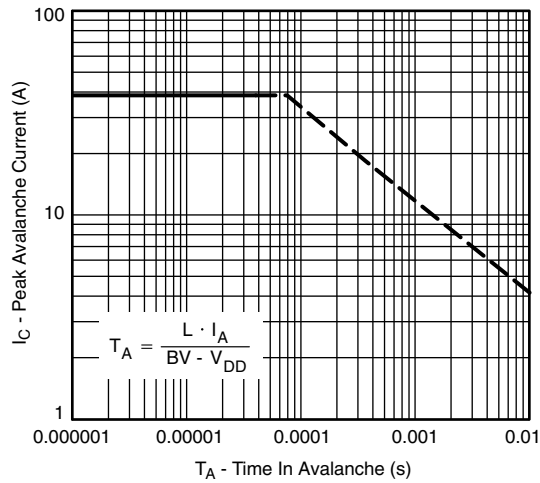
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



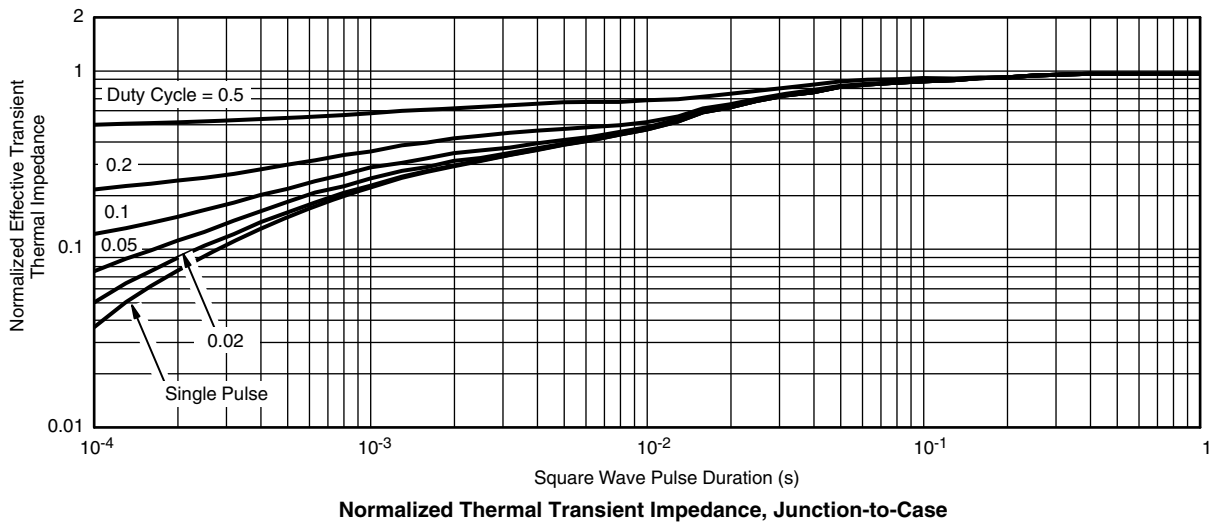
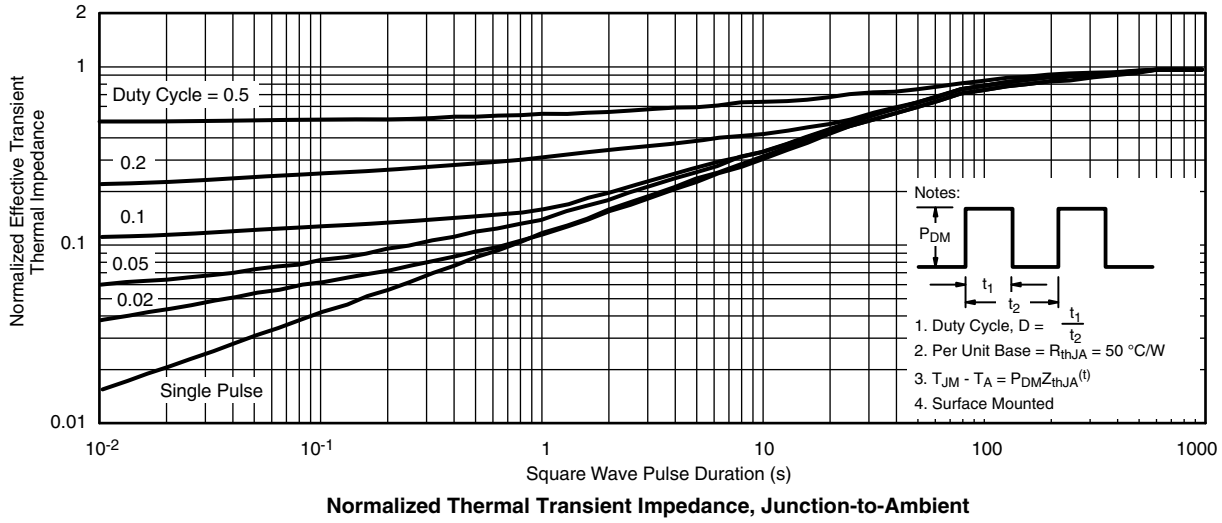
Single Pulse Power, Junction-to-Ambient



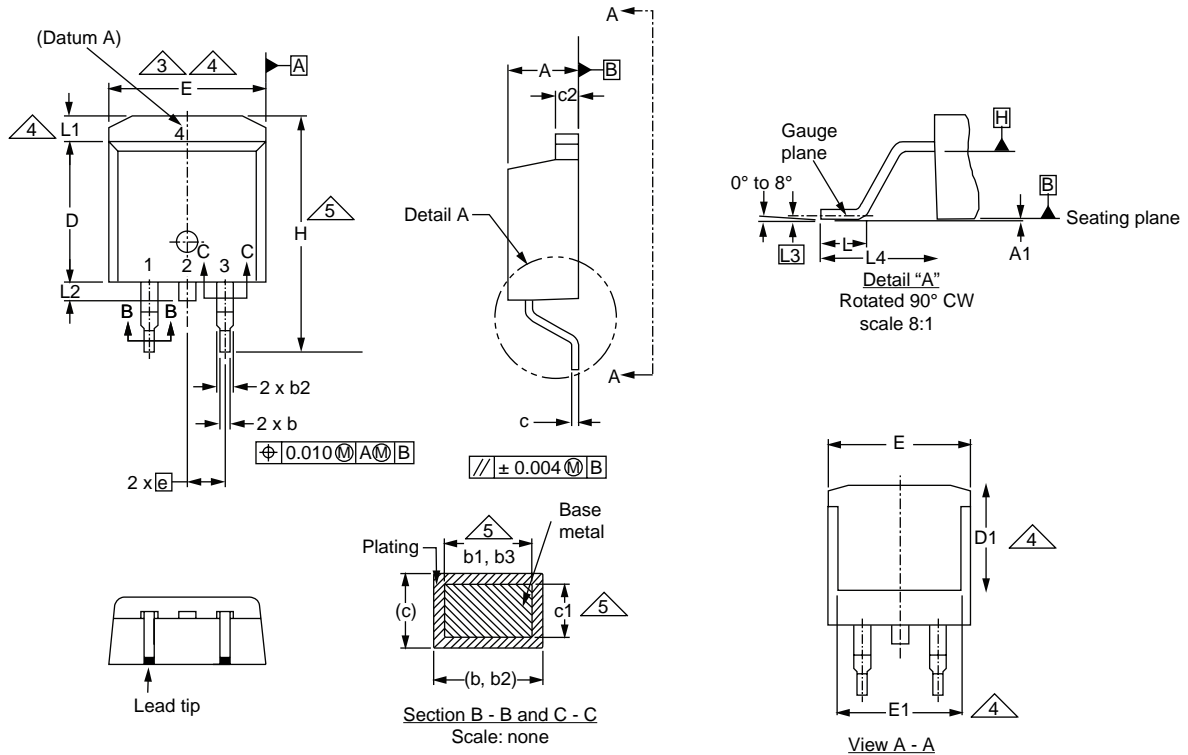
Single Pulse Avalanche Capability

* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



TO-263AB (HIGH VOLTAGE)



| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.06 | 4.83 | 0.160 | 0.190 |
| A1 | 0.00 | 0.25 | 0.000 | 0.010 |
| b | 0.51 | 0.99 | 0.020 | 0.039 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 |
| c | 0.38 | 0.74 | 0.015 | 0.029 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 |
| D | 8.38 | 9.65 | 0.330 | 0.380 |

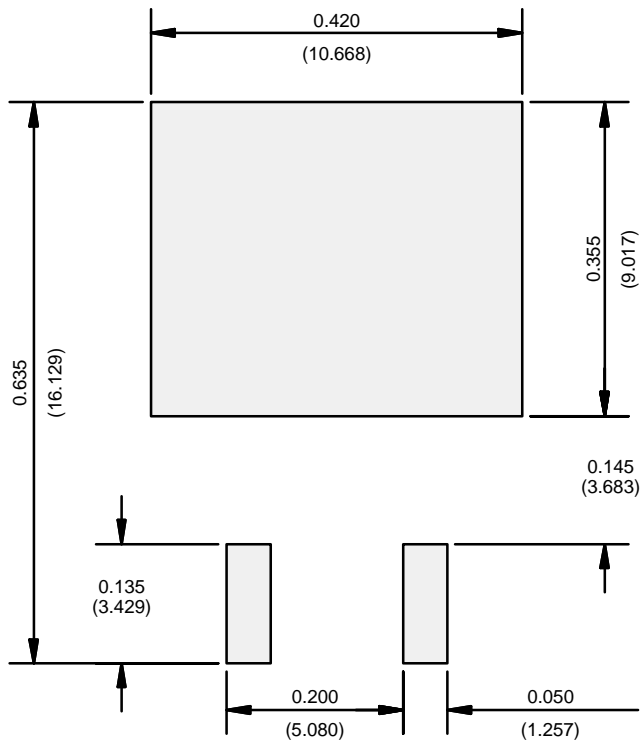
| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|-------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| D1 | 6.86 | - | 0.270 | - |
| E | 9.65 | 10.67 | 0.380 | 0.420 |
| E1 | 6.22 | - | 0.245 | - |
| e | 2.54 BSC | | 0.100 BSC | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | - | 1.65 | - | 0.066 |
| L2 | - | 1.78 | - | 0.070 |
| L3 | 0.25 BSC | | 0.010 BSC | |
| L4 | 4.78 | 5.28 | 0.188 | 0.208 |

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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